

Why Choose ALPHA[®] Solder Alloy?

Power Your Process with Confidence

The Industry's Most Comprehensive Solder Alloy Solutions

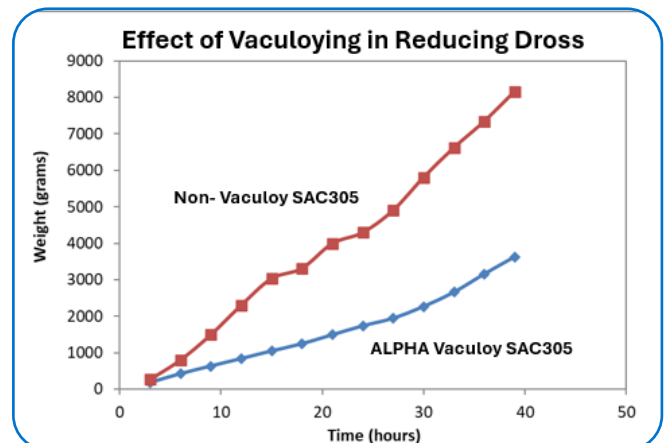
MacDermid Alpha Electronics Solutions provides the industry's broadest range of **high-purity solid solder alloys**, available in bar, wire, anode, and chunk forms.

Engineered for wave, selective, dip, and other molten soldering applications, these alloys are produced using Vaculoy[®] technology and formulated with proprietary performance-enhancing additives to deliver superior reliability and lower total cost. Whether you are optimizing for cost, performance, or compliance, the right alloy is available to support your production goals.



Key Features

- **Reduced Dross Formation:** Significantly lower solder waste and maintenance requirements, achieving up to 2.25x higher cost efficiency.
- **Exceptional Purity:** High-grade metals and precise Vaculoy controls reduce oxides, improve flow and minimize defects.
- **Superior Wetting and Hole Fill:** Delivers reliable solder coverage on complex finishes and assemblies, reducing defects and improving yield.
- **High-Reliability Formulations:** Tailored alloys balance performance and cost for demanding applications, ensuring long-term joint reliability.
- **Proven Performance:** Trusted for over 40 years across industries, with a full alloy portfolio, supporting reliable sourcing and supply chain continuity.
- **Sustainability Commitment:** Our alloys are REACH / RoHS compliant, using responsibly sourced conflict-free tin



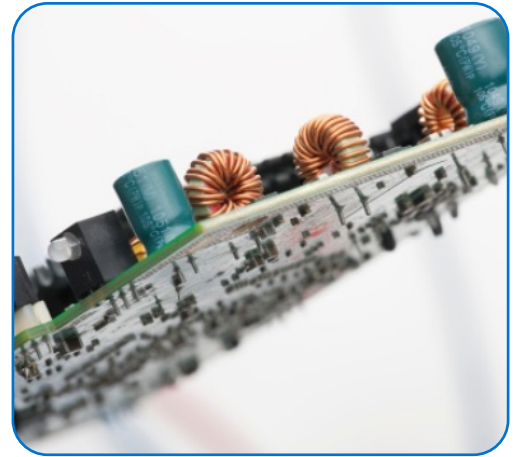
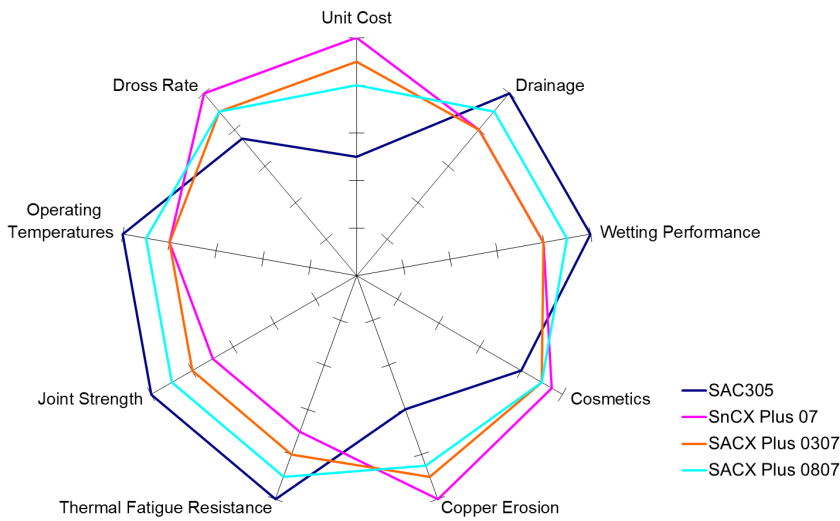
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MacDermid Alpha's Key Solid Solder Portfolio

Our range of proprietary alloys provides excellent thermomechanical reliability with proven performance in manufacturing across different assembly types and reliability requirements. Selecting the right alloy for your process helps lower overall cost while delivering stronger price stability.

Relative Comparison of SACX[®] Plus and SnCX[®] Plus Alloy Performance Attributes



| Alloy Category | Alloy Name | Key Product Description | Assembly Type Range | | |
|----------------|------------------------|---|---------------------|-----------|--------|
| | | | PCB Type | Thickness | Layers |
| High Silver | ALPHA SAC305 | • High mechanical reliability | Dual sided | > 2.4 mm | > 12 |
| | ALPHA SAC387 | | | | |
| | ALPHA SAC405 | | | | |
| Low Silver | ALPHA SACX Plus 0807 | • Low Silver 0.8% content • SAC305 like performance • Low Copper dissolution and drossing | Dual sided | > 2.4 mm | > 12 |
| | ALPHA SACX Plus 0307 | • Low Silver 0.3% content • Low Copper dissolution and drossing | Dual sided | < 2.4 mm | 4 - 12 |
| Silver Free | ALPHA SnCX Plus 07 | • Silver free to reduce cost • Low Copper dissolution and drossing | Dual sided | < 2.4 mm | 4 - 12 |
| | Kester K100LD | | | | |
| | ALPHA SnCu0.7 | • Industrial standard tin copper alloy | Single/Dual sided | < 1.6 mm | < 4 |
| Tin-Lead | ALPHA Sn63Pb37 HiFlo | • High purity for demanding leaded applications • Low drossing | Dual sided | > 2.4 mm | > 12 |
| | ALPHA Sn63Pb37 Vaculoy | • For general leaded application | Dual sided | < 2.4 mm | 4 - 12 |

